

SEMICONDUCTOR®

# **PN2369**

## **NPN Switching Transistor**

- This device is designed for high speed saturated switching at collector currents of 10mA to 100mA.
- Sourced from process 21.



PN2369

#### 1. Emitter 2. Base 3. Collector

# Absolute Maximum Ratings\* $T_a = 25^{\circ}C$ unless otherwise noted

| Symbol                            | Parameter  | Ratings   | Units |
|-----------------------------------|--|-----------|-------|
| V <sub>CEO</sub>                  | Collector-Emitter Voltage                        | 15        | V     |
| V <sub>CBO</sub>                  | Collector-Base Voltage                           | 40        | V     |
| V <sub>EBO</sub>                  | Emitter-Base Voltage                             | 4.5       | V     |
| I <sub>C</sub>                    | Collector Current - Continuous                   | 200       | mA    |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Junction Temperature Range | -55 ~ 150 | °C    |

\* This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### NOTES:

1) These rating are based on a maximum junction temperature of 150 degrees C.
2) These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics T<sub>a</sub>=25°C unless otherwise noted

| Symbol               | Parameter                              | Test Condition   | Min. | Max. | Units |
|----------------------|--|--|------|------|-------|
| Off Charac           | cteristics                             | •  |      | •    |       |
| V <sub>(BR)CEO</sub> | Collector-Emitter Breakdown Voltage *  | $I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$                               | 15   |      | V     |
| /(BR)CES             | Collector-Emitter Breakdown Voltage    | $I_{C} = 10\mu A, V_{BE} = 0$  | 40   |      | V     |
| (BR)CBO              | Collector-Base Breakdown Voltage       | $I_{C} = 10\mu A, I_{E} = 0$   | 40   |      | V     |
| (BR)EBO              | Emitter-Base Breakdown Voltage         | $I_{E} = 10\mu A, I_{C} = 0$   | 4.5  |      | V     |
| СВО                  | Collector Cutoff Current               | $V_{CB} = 20V, I_E = 0$  |      | 0.4  | μA    |
|                      |  | $V_{CB} = 20V, I_E = 0, T_a = 125^{\circ}C$                            |      | 30   | μΑ    |
| On Charac            | cteristics                             |  |      |      |       |
| <sup>)</sup> FE      | DC Current Gain *                      | I <sub>C</sub> = 10mA, V <sub>CE</sub> = 1.0V                          | 40   | 120  |       |
|                      |  | $I_{C} = 100 \text{mA}, V_{CE} = 2.0 \text{V}$                         | 20   |      |       |
| / <sub>CE(sat)</sub> | Collector-Emitter Saturation Voltage * | I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA                          |      | 0.25 | V     |
| / <sub>BE(sat)</sub> | Base-Emitter Saturation Voltage        | I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA                          | 0.7  | 0.85 | V     |
|                      | nal Characteristics                    |  |      | -    | •     |
| C <sub>obo</sub>     | Output Capacitance                     | $V_{CB} = 5.0V, I_E = 0, f = 1.0MHz$                                   |      | 4.0  | pF    |
| C <sub>ibo</sub>     | Input Capacitance                      | V <sub>EB</sub> = 0.5V, I <sub>C</sub> = 0, f = 1.0MHz                 |      | 5.0  | pF    |
| <sup>)</sup> fe      | Small -Signal Current Gain             | $I_{C}$ = 10mA, $V_{CE}$ = 10V, $R_{G}$ = 2.0k $\Omega$ , f = 100MHz   | 5.0  |      |       |
| Switching            | Characteristics                        | •  |      | •    |       |
| S                    | Storage Time                           | $I_{B1} = I_{B2} = I_{C} = 10 \text{mA}$                               |      | 13   | ns    |
| on                   | Turn-On Time                           | V <sub>CC</sub> = 3.0V, I <sub>C</sub> = 10mA, I <sub>B1</sub> = 3.0mA |      | 12   | ns    |
| off                  | Turn-Off Time                          | $V_{CC} = 3.0V, I_{C} = 10mA, I_{B1} = 3.0mA,$<br>$I_{B2} = 1.5mA$     |      | 18   | ns    |

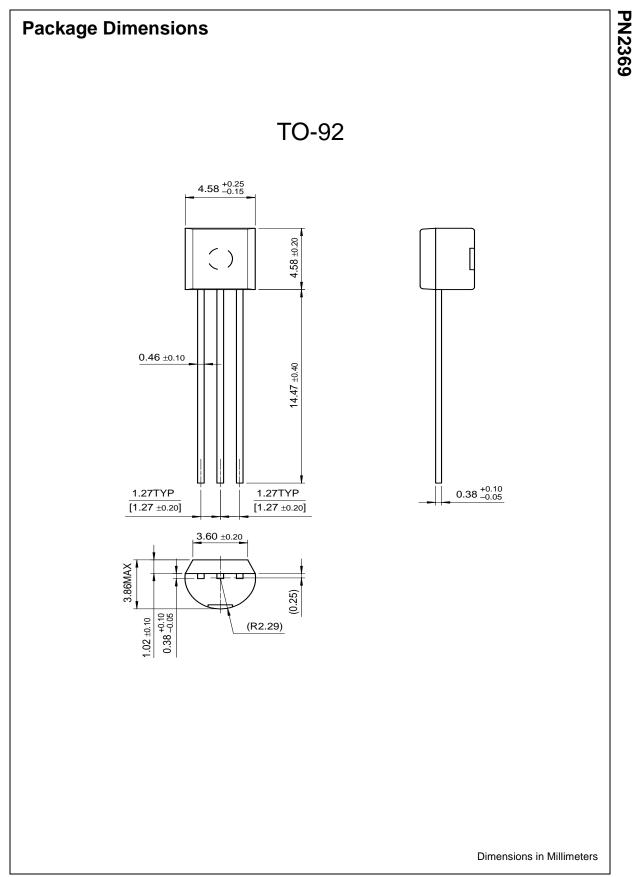
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| Thermal Characteristics T <sub>a</sub> =25°C unless otherwise noted |   |            |             |
|---|---|------------|-------------|
| Symbol  | Parameter                                     | Max.       | Units       |
| D   | Total Device Dissipation<br>Derate above 25°C | 350<br>2.8 | mW<br>mW/°C |
| ۲ <sub>θJC</sub>  | Thermal Resistance, Junction to Case          | 125        | °C/W        |
| R <sub>θJC</sub><br>R <sub>θJA</sub>                                | Thermal Resistance, Junction to Ambient       | 357        | °C/W        |



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|--------------------------|---------------------------|---|
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